

MOSFETs Silicon N-channel MOS (U-MOSVIII-H)

# SSM6K341NU

### 1. Applications

- · Power Management Switches
- · DC-DC Converters

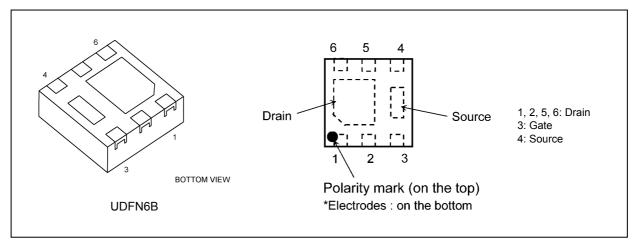
#### 2. Features

- (1) 4.0 V drive
- (2) Low drain-source on-resistance
  - :  $R_{\rm DS(ON)}$  = 28 m $\Omega$  (typ.) (@ $V_{\rm GS}$  = 10 V)

 $R_{\rm DS(ON)} = 36 \ {\rm m}\Omega \ ({\rm typ.}) \ (@V_{\rm GS} = 4.5 \ {\rm V})$ 

 $R_{\mathrm{DS(ON)}} = 43~\mathrm{m}\Omega$  (typ.) (@ $V_{\mathrm{GS}} = 4~\mathrm{V}$ )

### 3. Packaging and Pin Assignment



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# 4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Rating	Unit		
Drain-source voltage			$V_{DSS}$	60	V
Gate-source voltage			$V_{GSS}$	±20	
Drain current (DC)		(Note 1)	$I_D$	6	Α
Drain current (pulsed)		(Note 1), (Note 2)	$I_{DP}$	24	
Power dissipation		(Note 3)	$P_D$	1.25	W
Power dissipation	(t = 10 s)	(Note 3)	$P_{D}$	2.5	
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	28.9	mJ
Avalanche current			I <sub>AR</sub>	6	Α
Channel temperature			T <sub>ch</sub>	150	℃
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150 °C.
- Note 2: pulse width  $\leq$  1 ms, Duty  $\leq$  1 %
- Note 3: Device mounted on a 25.4 mm × 25.4 mm × 1.6 mm FR4 glass epoxy board (Cu pad: 645 mm<sup>2</sup>)
- Note 4:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25 °C (Initial state), L = 1 mH,  $R_G$  = 25  $\Omega$

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, R<sub>th(ch-a)</sub>, and the drain power dissipation, P<sub>D</sub>, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.



#### 5. Electrical Characteristics

### 5.1. Static Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$	_	_	±10	μА
Drain cut-off current		I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	1	
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	٧
Drain-source breakdown voltage	(Note 1)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	40	_	_	
Gate threshold voltage	(Note 2)	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.1 mA	1.5	_	2.5	
Drain-source on-resistance	(Note 3)	R <sub>DS(ON)</sub>	I <sub>D</sub> = 2 A, V <sub>GS</sub> = 4 V	_	43	69	mΩ
			I <sub>D</sub> = 3 A, V <sub>GS</sub> = 4.5 V	_	36	51	
			I <sub>D</sub> = 4 A, V <sub>GS</sub> = 10 V	_	28	36	

Note 1: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to below (0.1 mA for this device). Then, for normal switching operation,  $V_{GS(ON)}$  must be higher than  $V_{th}$ , and  $V_{GS(OFF)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$ .

Take this into consideration when using the device.

Note 3: Pulse measurement.

# 5.2. Dynamic Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$	_	550	_	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz	_	35	_	
Output capacitance	C <sub>oss</sub>			300	_	
Switching time (rise time)	t <sub>r</sub>	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 3 A,	_	48	_	ns
Switching time (turn-on time)	t <sub>on</sub>	$V_{GS}$ = 0 to 4.5 V, $R_{G}$ = 50 Ω Duty ≤ 1 %,Input: $t_{r}$ , $t_{f}$ < 5 ns,	_	63	_	
Switching time (fall time)	t <sub>f</sub>	Common source,		6	_	
Switching time (turn-off time)	t <sub>off</sub>	See Chapter 5.3.		18	_	

#### 5.3. Switching Time Test Circuit

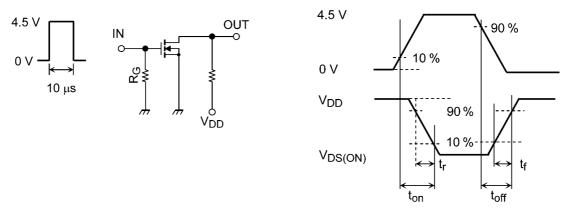


Fig. 5.3.1 Switching Time Test Circuit

Fig. 5.3.2 Input Waveform/Output Waveform

### 5.4. Gate Charge Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} = 48 \text{ V}, I_D = 2 \text{ A},$	_	9.3		nC
Gate-source charge 1	Q <sub>gs1</sub>	V <sub>GS</sub> = 10 V	_	1.8		
Gate-drain charge	Q <sub>gd</sub>		_	2.0		

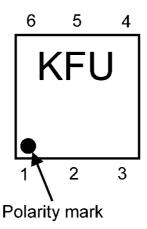


# 5.5. Source-Drain Characteristics (Unless otherwise specified, Ta = 25 °C)

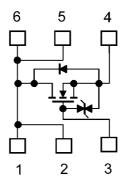
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	(Note 1)	$V_{DSF}$	$I_D = -4 A, V_{GS} = 0 V$	_	-0.84	-1.5	٧

Note 1: Pulse measurement.

### 6. Marking

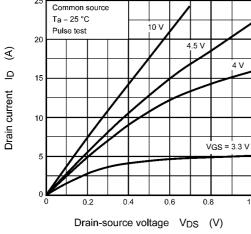


### 7. Internal Circuit





### 8. Characteristics Curves (Note)





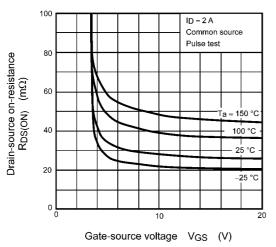


Fig. 8.3 R<sub>DS(ON)</sub> - V<sub>GS</sub>

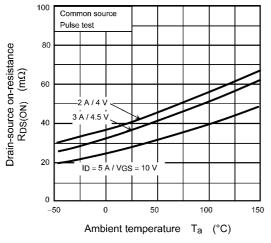


Fig. 8.5 R<sub>DS(ON)</sub> - T<sub>a</sub>

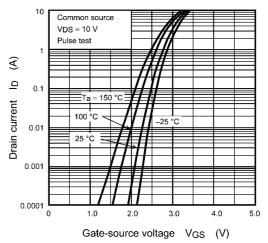


Fig. 8.2 I<sub>D</sub> - V<sub>GS</sub>

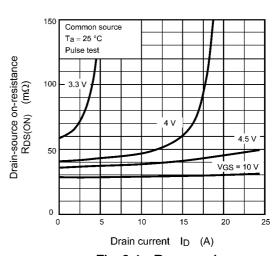


Fig. 8.4 R<sub>DS(ON)</sub> - I<sub>D</sub>

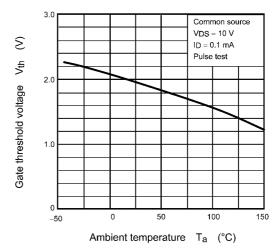
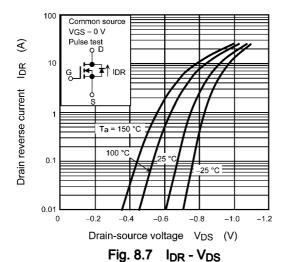
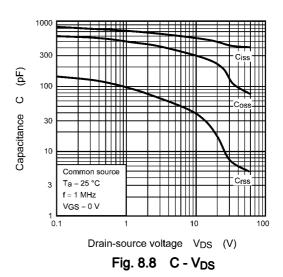
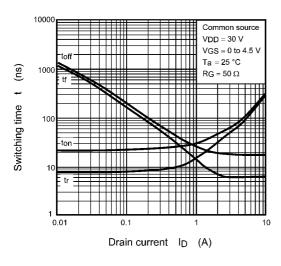


Fig. 8.6 V<sub>th</sub> - T<sub>a</sub>









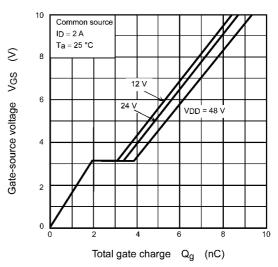


Fig. 8.9 t - I<sub>D</sub>

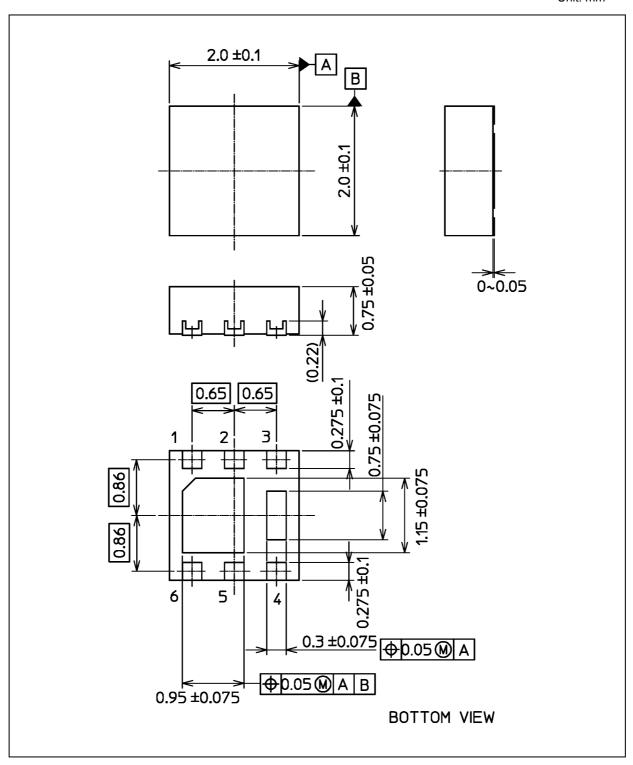
Fig. 8.10 Dynamic Input Characteristics

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



### **Package Dimensions**

Unit: mm



Weight: 8.5 mg (typ.)

	Package Name(s)
Nickname: UDFN6B	

Rev.6.0



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